MSD601-RT1, MSD601-ST1

Preferred Device

NPN General Purpose Amplifier Transistors Surface Mount

Features

• Pb-Free Packages are Available



Rating	Symbol	Value	Unit
Collector – Base Voltage	V _{(BR)CBO}	60	Vdc
Collector – Emitter Voltage	V _{(BR)CEO}	50	Vdc
Emitter – Base Voltage	V _{(BR)EBO}	7.0	Vdc
Collector Current – Continuous	Ι _C	100	mAdc
Collector Current – Peak	I _{C(P)}	200	mAdc

THERMAL CHARACTERISTICS

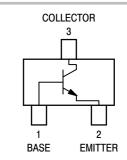
Characteristic	Symbol	Max	Unit
Power Dissipation	PD	200	mW
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	-55 ~ +150	°C

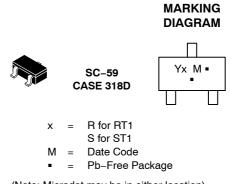
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

MSD601-RT1, MSD601-ST1

ELECTRICAL CHARACTERISTICS (T_A = 25° C)

Characteristic	Symbol	Min	Max	Unit
Collector – Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	50	-	Vdc
Collector – Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	60	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	7.0	-	Vdc
Collector – Base Cutoff Current (V_{CB} = 45 Vdc, I _E = 0)	I _{CBO}	-	0.1	μAdc
Collector – Emitter Cutoff Current (V_{CE} = 10 Vdc, I _B = 0)	I _{CEO}	-	100	nAdc
$ \begin{array}{l} \text{DC Current Gain (Note 1)} \\ (\text{V}_{\text{CE}} = 10 \ \text{Vdc}, \ \text{I}_{\text{C}} = 2.0 \ \text{mAdc}) \\ \qquad $	h _{FE1} h _{FE2}	210 290 90	340 460 -	-
Collector – Emitter Saturation Voltage (I _C = 100 mAdc, I _B = 10 mAdc)	V _{CE(sat)}	-	0.5	Vdc

1. Pulse Test: Pulse Width \leq 300 µs, D.C. \leq 2%.

ORDERING INFORMATION

Device	Package	Shipping [†]
MSD-601RT1	SC-59	3000 / Tape & Reel
MSD-601RT1G	SC-59 (Pb-Free)	3000 / Tape & Reel
MSD-601ST1	SC-59	3000 / Tape & Reel
MSD-601ST1G	SC-59 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





SCALE 2:1



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SC-59 CASE 318D-04 **ISSUE H**

DATE 28 JUN 2012

NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.15	1.30	0.039	0.045	0.051
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.35	0.43	0.50	0.014	0.017	0.020
С	0.09	0.14	0.18	0.003	0.005	0.007
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
е	1.70	1.90	2.10	0.067	0.075	0.083
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.80	3.00	0.099	0.110	0.118

GENERIC **MARKING DIAGRAM**



= Specific Device Code XXX Μ = Date Code

= Pb-Free Package*

(*Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. BASE	PIN 1. ANODE	PIN 1. ANODE
2. EMITTER	2. N.C.	2. ANODE
3. COLLECTOR	3. CATHODE	3. CATHODE
Style 4:	Style 5:	STYLE 6:
Pin 1. Cathode	Pin 1. Cathode	PIN 1. ANODE
2. n.C.	2. Cathode	2. CATHODE
3. Anode	3. Anode	3. ANODE/CATHODE

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